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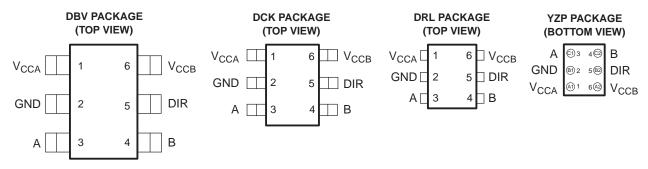
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SN74LVC1T45

### FEATURES

- Available in the Texas Instruments NanoFree<sup>™</sup> Package
- **Fully Configurable Dual-Rail Design Allows** Each Port to Operate Over the Full 1.65-V to 5.5-V Power-Supply Range
- V<sub>cc</sub> Isolation Feature If Either V<sub>cc</sub> Input Is at GND, Both Ports Are in the High-Impedance State
- DIR Input Circuit Referenced to V<sub>CCA</sub>
- Low Power Consumption, 4-µA Max Icc •
- ±24-mA Output Drive at 3.3 V
- Ioff Supports Partial-Power-Down Mode Operation

- Max Data Rates
  - 420 Mbps (3.3-V to 5-V Translation)
  - 210 Mbps (Translate to 3.3 V)
  - 140 Mbps (Translate to 2.5 V)
  - 75 Mbps (Translate to 1.8 V)
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)
  - 1000-V Charged-Device Model (C101)



See mechanical drawings for dimensions.

## DESCRIPTION/ORDERING INFORMATION

This single-bit noninverting bus transceiver uses two separate configurable power-supply rails. The A port is designed to track V<sub>CCA</sub>. V<sub>CCA</sub> accepts any supply voltage from 1.65 V to 5.5 V. The B port is designed to track V<sub>CCB</sub>. V<sub>CCB</sub> accepts any supply voltage from 1.65 V to 5.5 V. This allows for universal low-voltage bidirectional translation between any of the 1.8-V, 2.5-V, 3.3-V, and 5-V voltage nodes.

#### **ORDERING INFORMATION**

T <sub>A</sub>	PACKAGE <sup>(1)</sup>		ORDERABLE PART NUMBER	TOP-SIDE MARKING <sup>(2)</sup>
	NanoFree™ – WCSP (DSBGA) 0.23-mm Large Bump – YZP (Pb-free)	Reel of 3000	SN74LVC1T45YZPR	TA_
	SOT (SOT-23) – DBV	Reel of 3000	SN74LVC1T45DBVR	CT1
–40°C to 85°C	SOT (SOT-23) - DBV	Reel of 250	SN74LVC1T45DBVT	
	SOT (SC-70) – DCK	Reel of 3000	SN74LVC1T45DCKR	
	SOT (SC-70) - DCK	Reel of 250	SN74LVC1T45DCKT	TA_
	SOT (SOT-533) – DRL	Reel of 4000	SN74LVC1T45DRLR	

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

DBV/DCK/DRL: The actual top-side marking has one additional character that designates the assembly/test site. (2)YZP: The actual top-side marking has three preceding characters to denote year, month, and sequence code, and one following character to designate the assembly/test site. Pin 1 identifier indicates solder-bump composition (1 = SnPb, • = Pb-free).



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet. NanoFree is a trademark of Texas Instruments.



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### **DESCRIPTION/ORDERING INFORMATION (CONTINUED)**

The SN74LVC1T45 is designed for asynchronous communication between two data buses. The logic levels of the direction-control (DIR) input activate either the B-port outputs or the A-port outputs. The device transmits data from the A bus to the B bus when the B-port outputs are activated and from the B bus to the A bus when the A-port outputs are activated. The input circuitry on both A and B ports always is active and must have a logic HIGH or LOW level applied to prevent excess  $I_{CC}$  and  $I_{CCZ}$ .

The SN74LVC1T45 is designed so that the DIR input is powered by V<sub>CCA</sub>.

This device is fully specified for partial-power-down applications using I<sub>off</sub>. The I<sub>off</sub> circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

The  $V_{CC}$  isolation feature ensures that if either  $V_{CC}$  input is at GND, then both ports are in the high-impedance state.

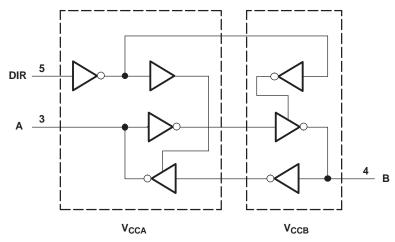
NanoFree<sup>™</sup> package technology is a major breakthrough in IC packaging concepts, using the die as the package.

INPUT DIR	OPERATION
L	B data to A bus
н	A data to B bus

#### FUNCTION TABLE<sup>(1)</sup>

(1) Input circuits of the data I/Os always are active.

#### LOGIC DIAGRAM (POSITIVE LOGIC)





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## Absolute Maximum Ratings<sup>(1)</sup>

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
$V_{CCA} V_{CCB}$	Supply voltage range		-0.5	6.5	V
VI	Input voltage range <sup>(2)</sup>		-0.5	6.5	V
Vo	Voltage range applied to any output in the high-impedance or pow	er-off state <sup>(2)</sup>	-0.5	6.5	V
V	V(a)	A port	-0.5	V <sub>CCA</sub> + 0.5	V
Vo	Voltage range applied to any output in the high or low state $^{(2)}$	B port	-0.5	V <sub>CCB</sub> + 0.5	V
I <sub>IK</sub>	Input clamp current	V <sub>1</sub> < 0		-50	mA
I <sub>OK</sub>	Output clamp current	V <sub>O</sub> < 0		-50	mA
I <sub>O</sub>	Continuous output current	÷		±50	mA
	Continuous current through V <sub>CC</sub> or GND			±100	mA
		DBV package		165	
0		DCK package		259	0000
$\theta_{JA}$	Package thermal impedance <sup>(4)</sup>	DRL package		142	°C/W
		YZP package		123	
T <sub>stg</sub>	Storage temperature range		-65	150	°C

(1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

(2)

(3) The value of V<sub>CC</sub> is provided in the recommended operating conditions table.

(4) The package thermal impedance is calculated in accordance with JESD 51-7.



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## **Recommended Operating Conditions**<sup>(1)(2)(3)</sup>

			V <sub>CCI</sub>	V <sub>cco</sub>	MIN	MAX	UNIT
V <sub>CCA</sub>	Supply voltage				1.65	5.5	V
V <sub>CCB</sub>	Supply voltage				1.65	5.5	v
			1.65 V to 1.95 V		$V_{CCI}  imes 0.65$		
	High-level	Data issues (4)	2.3 V to 2.7 V		1.7		V
VIH	input voltage	Data inputs <sup>(4)</sup>	3 V to 3.6 V		2		v
			4.5 V to 5.5 V		$V_{CCI}  imes 0.7$		
			1.65 V to 1.95 V			$V_{CCI}  imes 0.35$	
	Low-level	Data insuta(4)	2.3 V to 2.7 V			0.7	V
V <sub>IL</sub>	input voltage	Data inputs <sup>(4)</sup>	3 V to 3.6 V			0.8	v
			4.5 V to 5.5 V			$V_{CCI}  imes 0.3$	
			1.65 V to 1.95 V		$V_{CCA}  imes 0.65$		
. ,	High-level	DIR	2.3 V to 2.7 V		1.7		
V <sub>IH</sub>	input voltage	(referenced to $V_{CCA}$ ) <sup>(5)</sup>	3 V to 3.6 V		2		V
			4.5 V to 5.5 V		$V_{CCA}  imes 0.7$		
			1.65 V to 1.95 V			$V_{CCA}  imes 0.35$	
	Low-level	DIR	2.3 V to 2.7 V			0.7	
V <sub>IL</sub>	input voltage	(referenced to $V_{CCA}$ ) <sup>(5)</sup>	3 V to 3.6 V			0.8	V
			4.5 V to 5.5 V			$V_{CCA}  imes 0.3$	
VI	Input voltage				0	5.5	V
Vo	Output voltage				0	V <sub>cco</sub>	V
				1.65 V to 1.95 V		-4	
	Link laurel euteurt -			2.3 V to 2.7 V		-8	
ОН	High-level output o	current		3 V to 3.6 V		-24	mA
				4.5 V to 5.5 V		-32	
				1.65 V to 1.95 V		4	
				2.3 V to 2.7 V		8	
OL	Low-level output c	urrent		3 V to 3.6 V		24	mA
				4.5 V to 5.5 V		32	
			1.65 V to 1.95 V			20	
		Data insuta	2.3 V to 2.7 V			20	
∆t/∆v	Input transition rise or fall rate	Data inputs	3 V to 3.6 V			10	ns/V
		e or fall rate	4.5 V to 5.5 V			5	
		Control inputs	1.65 V to 5.5 V			5	
T <sub>A</sub>	Operating free-air	temperature			-40	85	°C

V<sub>CCI</sub> is the V<sub>CC</sub> associated with the input port.
 V<sub>CCO</sub> is the V<sub>CC</sub> associated with the output port.
 All unused data inputs of the device must be held at V<sub>CCI</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.
 For V<sub>CCI</sub> values not specified in the data sheet, V<sub>IH</sub> min = V<sub>CCI</sub> × 0.7 V, V<sub>IL</sub> max = V<sub>CCI</sub> × 0.3 V.
 For V<sub>CCI</sub> values not specified in the data sheet, V<sub>IH</sub> min = V<sub>CCA</sub> × 0.7 V, V<sub>IL</sub> max = V<sub>CCA</sub> × 0.3 V.

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# Electrical Characteristics<sup>(1)(2)</sup>

over recommended operating free-air temperature range (unless otherwise noted)

	METER	TEST CONDI		V	V	т	_ <sub>A</sub> = 25°C	;	–40°C to	85°C	UNIT
PARA	METER	TEST CONDI		V <sub>CCA</sub>	V <sub>CCB</sub>	MIN	TYP	MAX	MIN	MAX	UNIT
		I <sub>OH</sub> = -100 μA		1.65 V to 4.5 V	1.65 V to 4.5 V				V <sub>CCO</sub> - 0.1		
		$I_{OH} = -4 \text{ mA}$		1.65 V	1.65 V				1.2		
V <sub>OH</sub>		I <sub>OH</sub> = -8 mA	$V_I = V_{IH}$	2.3 V	2.3 V				1.9		V
		I <sub>OH</sub> = -24 mA		3 V	3 V				2.4		
		I <sub>OH</sub> = -32 mA		4.5 V	4.5 V				3.8		
		I <sub>OL</sub> = 100 μA		1.65 V to 4.5 V	1.65 V to 4.5 V					0.1	
		$I_{OL} = 4 \text{ mA}$		1.65 V	1.65 V					0.45	
V <sub>OL</sub>		I <sub>OL</sub> = 8 mA	$V_I = V_{IL}$	2.3 V	2.3 V					0.3	V
		I <sub>OL</sub> = 24 mA		3 V	3 V					0.55	
		I <sub>OL</sub> = 32 mA		4.5 V	4.5 V					0.55	
I <sub>I</sub>	DIR	$V_I = V_{CCA}$ or GND		1.65 V to 5.5 V	1.65 V to 5.5 V			±1		±2	μA
	A port			0 V	0 to 5.5 V			±1		±2	•
off	B port	$V_{\rm I}$ or $V_{\rm O}$ = 0 to 5.5	V	0 to 5.5 V	0 V			±1		±2	μA
I <sub>oz</sub>	A or B port	$V_{O} = V_{CCO}$ or GND	)	1.65 V to 5.5 V	1.65 V to 5.5 V			±1		±2	μA
	-			1.65 V to 5.5 V	1.65 V to 5.5 V					3	
I <sub>CCA</sub>		$V_I = V_{CCI}$ or GND,	$I_{O} = 0$	5.5 V	0 V					2	μA
				0 V	5.5 V					-2	
				1.65 V to 5.5 V	1.65 V to 5.5 V					3	
I <sub>CCB</sub>		$V_I = V_{CCI}$ or GND,	$I_{O} = 0$	5.5 V	0 V					-2	μA
				0 V	5.5 V					2	
I <sub>CCA</sub> + (see Ta	I <sub>CCB</sub> able 1)	$V_{I} = V_{CCI}$ or GND,	$I_{O} = 0$	1.65 V to 5.5 V	1.65 V to 5.5 V					4	μΑ
	A port	A port at $V_{CCA} - 0$ . DIR at $V_{CCA}$ , B por	6 V, t = open							50	
∆I <sub>CCA</sub>	DIR	DIR at $V_{CCA} - 0.6$ M B port = open, A port at $V_{CCA}$ or G	V,	3 V to 5.5 V	3 V to 5.5 V					50	μA
ΔI <sub>CCB</sub>	B port	B port at $V_{CCB} - 0$ . DIR at GND, A port = open	6 V,	3 V to 5.5 V	3 V to 5.5 V					50	μA
C <sub>i</sub>	DIR	$V_I = V_{CCA} \text{ or } GND$		3.3 V	3.3 V		2.5				pF
C <sub>io</sub>	A or B port	$V_{O} = V_{CCA/B}$ or GN	D	3.3 V	3.3 V		6				pF

 $\begin{array}{ll} \mbox{(1)} & V_{CCO} \mbox{ is the } V_{CC} \mbox{ associated with the output port.} \\ \mbox{(2)} & V_{CCI} \mbox{ is the } V_{CC} \mbox{ associated with the input port.} \end{array}$ 

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#### **Switching Characteristics**

over recommended operating free-air temperature range, V<sub>CCA</sub> = 1.8 V  $\pm$  0.15 V (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CCB</sub> = ± 0.15	1.8 V 5 V	V <sub>ССВ</sub> = ± 0.2		V <sub>CCB</sub> = ± 0.3		V <sub>ССВ</sub> = ± 0.5		UNIT
	(INPUT)	(001901)	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
t <sub>PLH</sub>	А	В	3	17.7	2.2	10.3	1.7	8.3	1.4	7.2	~~~
t <sub>PHL</sub>	A	Б	2.8	14.3	2.2	8.5	1.8	7.1	1.7	7	ns
t <sub>PLH</sub>	В	А	3	17.7	2.3	16	2.1	15.5	1.9	15.1	20
t <sub>PHL</sub>	Б	A	2.8	14.3	2.1	12.9	2	12.6	1.8	12.2	ns
t <sub>PHZ</sub>	פוס	٨	5.2	19.4	4.8	18.5	4.7	18.4	5.1	17.1	20
t <sub>PLZ</sub>	DIR	DIR A	2.3	10.5	2.1	10.5	2.4	10.7	3.1	10.9	ns
t <sub>PHZ</sub>	DIR	В	7.4	21.9	4.9	11.5	4.6	10.3	2.8	8.2	20
t <sub>PLZ</sub>	DIR	Б	4.2	16	3.7	9.2	3.3	8.4	2.4	6.4	ns
t <sub>PZH</sub> <sup>(1)</sup>	פוס	٨		33.7		25.2		23.9		21.5	20
t <sub>PZL</sub> <sup>(1)</sup>	DIR	DIR A		36.2		24.4		22.9		20.4	ns
t <sub>PZH</sub> <sup>(1)</sup>		В		28.2		20.8		19		18.1	~~~
t <sub>PZL</sub> <sup>(1)</sup>	DIR	В		33.7		27		25.5		24.1	ns

(1) The enable time is a calculated value, derived using the formula shown in the enable times section.

### **Switching Characteristics**

over recommended operating free-air temperature range, V<sub>CCA</sub> = 2.5 V  $\pm$  0.2 V (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CCB</sub> = ± 0.15		V <sub>ССВ</sub> = ± 0.2		V <sub>CCB</sub> = ± 0.3		V <sub>CCB</sub> = ± 0.5		UNIT
	(INPUT)	(001201)	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
t <sub>PLH</sub>	А	В	2.3	16	1.5	8.5	1.3	6.4	1.1	5.1	ns
t <sub>PHL</sub>	A	В	2.1	12.9	1.4	7.5	1.3	5.4	0.9	4.6	115
t <sub>PLH</sub>	В	А	2.2	10.3	1.5	8.5	1.4	8	1	7.5	20
t <sub>PHL</sub>	Б	A	2.2	8.5	1.4	7.5	1.3	7	0.9	6.2	ns
t <sub>PHZ</sub>	DIR	А	3	8.1	3.1	8.1	2.8	8.1	3.2	8.1	ns
t <sub>PLZ</sub>	DIK	A	1.3	5.9	1.3	5.9	1.3	5.9	1	5.8	115
t <sub>PHZ</sub>	DIR	В	6.5	23.7	4.1	11.4	3.9	10.2	2.4	7.1	20
t <sub>PLZ</sub>	DIR	D	3.9	18.9	3.2	9.6	2.8	8.4	1.8	5.3	ns
t <sub>PZH</sub> <sup>(1)</sup>	DIR	٥		29.2		18.1		16.4		12.8	20
t <sub>PZL</sub> <sup>(1)</sup>	DIR	A		32.2		18.9		17.2		13.3	ns
t <sub>PZH</sub> <sup>(1)</sup>	DIR	DIR B		21.9		14.4		12.3		10.9	20
t <sub>PZL</sub> <sup>(1)</sup>	DIR	Б		21		15.6		13.5		12.7	ns

(1) The enable time is a calculated value, derived using the formula shown in the enable times section.

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### **Switching Characteristics**

over recommended operating free-air temperature range, V\_{CCA} = 3.3 V  $\pm$  0.3 V (see Figure 1)

			-	COA			-	-			
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CCB</sub> = 1 ± 0.15	1.8 V 5 V	V <sub>ССВ</sub> = ± 0.2	2.5 V 2 V	V <sub>CCB</sub> = ± 0.3	3.3 V V	V <sub>ССВ</sub> = ± 0.5		UNIT
	(INPUT)	(001901)	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
t <sub>PLH</sub>	А	В	2.1	15.5	1.4	8	0.7	5.8	0.7	4.4	20
t <sub>PHL</sub>	A	Б	2	12.6	1.3	7	0.8	5	0.7	4	ns
t <sub>PLH</sub>	В	А	1.7	8.3	1.3	6.4	0.7	5.8	0.6	5.4	ns
t <sub>PHL</sub>	В	A	1.8	7.1	1.3	5.4	0.8	5	0.7	4.5	115
t <sub>PHZ</sub>	DIR	А	2.9	7.3	3	7.3	2.8	7.3	3.4	7.3	20
t <sub>PLZ</sub>	DIK	A	1.8	5.6	1.6	5.6	2.2	5.7	2.2	5.7	ns
t <sub>PHZ</sub>	DIR	В	5.4	20.5	3.9	10.1	2.9	8.8	2.4	6.8	20
t <sub>PLZ</sub>	DIK	Б	3.3	14.5	2.9	7.8	2.4	7.1	1.7	4.9	ns
t <sub>PZH</sub> <sup>(1)</sup>	DIR	А		22.8		14.2		12.9		10.3	20
t <sub>PZL</sub> <sup>(1)</sup>	DIK	A		27.6		15.5		13.8		11.3	ns
t <sub>PZH</sub> <sup>(1)</sup>	DIR	В		21.1		13.6		11.5		10.1	20
t <sub>PZL</sub> <sup>(1)</sup>	DIR	Б		19.9		14.3		12.3		11.3	ns

(1) The enable time is a calculated value, derived using the formula shown in the enable times section.

### **Switching Characteristics**

over recommended operating free-air temperature range,  $V_{CCA} = 5 \text{ V} \pm 0.5 \text{ V}$  (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CCB</sub> = ± 0.15		V <sub>CCB</sub> = ± 0.2		V <sub>CCB</sub> = ± 0.3		V <sub>CCB</sub> = ± 0.5	5 V V	UNIT
	(INPUT)	(001901)	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
t <sub>PLH</sub>	А	В	1.9	15.1	1	7.5	0.6	5.4	0.5	3.9	ns
t <sub>PHL</sub>	A	Б	1.8	12.2	0.9	6.2	0.7	4.5	0.5	3.5	115
t <sub>PLH</sub>	В	А	1.4	7.2	1	5.1	0.7	4.4	0.5	3.9	20
t <sub>PHL</sub>	Б	A	1.7	7	0.9	4.6	0.7	4	0.5	3.5	ns
t <sub>PHZ</sub>	DIR	А	2.1	5.4	2.2	5.4	2.2	5.5	2.2	5.4	ns
t <sub>PLZ</sub>	DIK	~	0.9	3.8	1	3.8	1	3.7	0.9	3.7	115
t <sub>PHZ</sub>	DIR	В	4.8	20.2	2.5	9.8	1	8.5	2.5	6.5	20
t <sub>PLZ</sub>	DIK	Б	4.2	14.8	2.5	7.4	2.5	7	1.6	4.5	ns
t <sub>PZH</sub> <sup>(1)</sup>	DIR	А		22		12.5		11.4		8.4	20
t <sub>PZL</sub> <sup>(1)</sup>	DIR	DIR A		27.2		14.4		12.5		10	ns
t <sub>PZH</sub> <sup>(1)</sup>	פוט	DIR B		18.9		11.3		9.1		7.6	ns
t <sub>PZL</sub> <sup>(1)</sup>	DIK	ы		17.6		11.6		10		8.6	115

(1) The enable time is a calculated value, derived using the formula shown in the enable times section.

## **Operating Characteristics**

 $T_A = 25^{\circ}C$ 

	PARAMETER	TEST CONDITIONS	V <sub>CCA</sub> = V <sub>CCB</sub> = 1.8 V TYP	V <sub>CCA</sub> = V <sub>CCB</sub> = 2.5 V TYP	V <sub>CCA</sub> = V <sub>CCB</sub> = 3.3 V TYP	V <sub>CCA</sub> = V <sub>CCB</sub> = 5 V TYP	UNIT
- (1)	A-port input, B-port output	$C_L = 0 pF,$	3	4	4	4	_
C <sub>pdA</sub> <sup>(1)</sup>	B-port input, A-port output	f = 10 MHz, t <sub>r</sub> = t <sub>f</sub> = 1 ns	18	19	20	21	pF
- (4)	A-port input, B-port output	$C_L = 0 pF$ ,	18	19	20	21	_
C <sub>pdB</sub> <sup>(1)</sup>	B-port input, A-port output	f = 10 MHz, t <sub>r</sub> = t <sub>f</sub> = 1 ns	3	4	4	4	pF

(1) Power dissipation capacitance per transceiver

### SN74LVC1T45 SINGLE-BIT DUAL-SUPPLY BUS TRANSCEIVER WITH CONFIGURABLE VOLTAGE TRANSLATION AND 3-STATE OUTPUTS SCES515H-DECEMBER 2003-REVISED JANUARY 2007



**Power-Up Considerations** 

A proper power-up sequence always should be followed to avoid excessive supply current, bus contention, oscillations, or other anomalies. To guard against such power-up problems, take the following precautions:

- 1. Connect ground before any supply voltage is applied.
- 2. Power up  $V_{CCA}$ .
- 3.  $V_{CCB}$  can be ramped up along with or after  $V_{CCA}$ .

V			V <sub>CCA</sub>			UNIT
V <sub>CCB</sub>	0 V	1.8 V	2.5 V	3.3 V	5 V	UNIT
0 V	0	<1	<1	<1	<1	
1.8 V	<1	<2	<2	<2	2	
2.5 V	<1	<2	<2	<2	<2	μA
3.3 V	<1	<2	<2	<2	<2	1
5 V	<1	2	<2	<2	<2	1

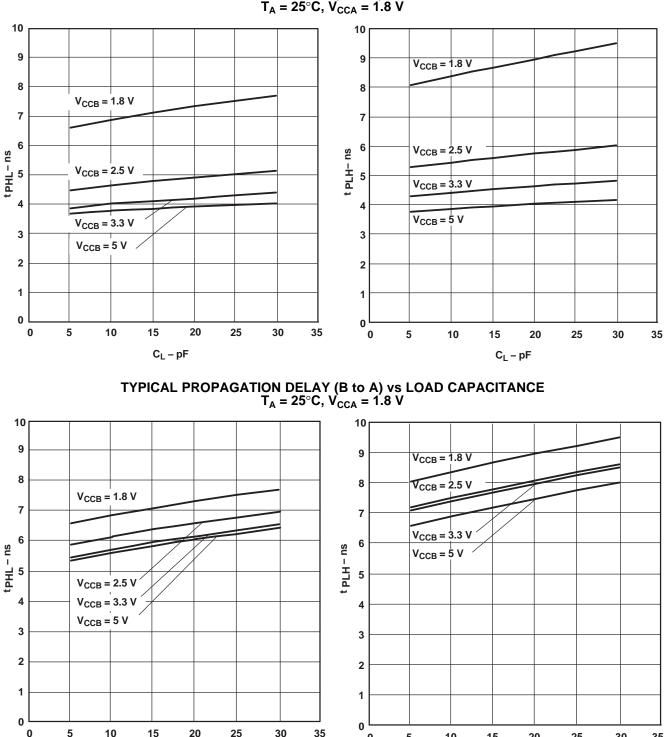
#### Table 1. Typical Total Static Power Consumption (I<sub>CCA</sub> + I<sub>CCB</sub>)

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## SN74LVC1T45 SINGLE-BIT DUAL-SUPPLY BUS TRANSCEIVER WITH CONFIGURABLE VOLTAGE TRANSLATION AND 3-STATE OUTPUTS

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#### **TYPICAL CHARACTERISTICS**



TYPICAL PROPAGATION DELAY (A to B) vs LOAD CAPACITANCE  $T_{A}$  = 25°C,  $V_{CCA}$  = 1.8 V

 $C_L - pF$ 

0

5

10

15

20

 $C_L - pF$ 

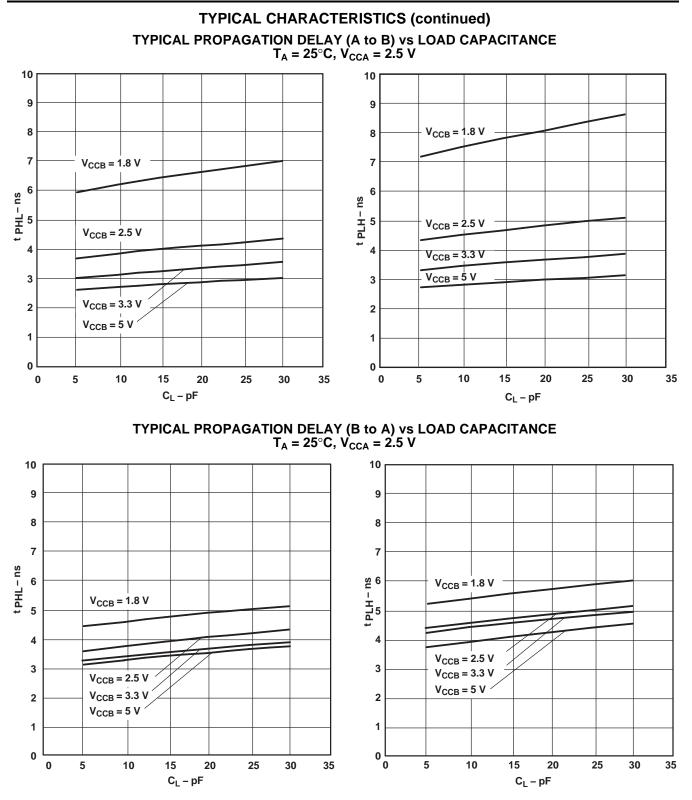
35

25

30



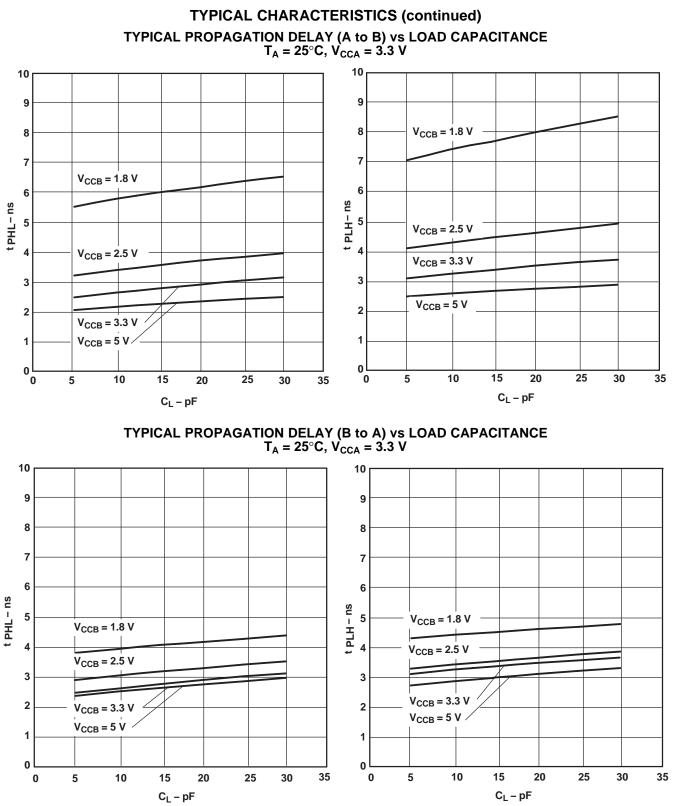
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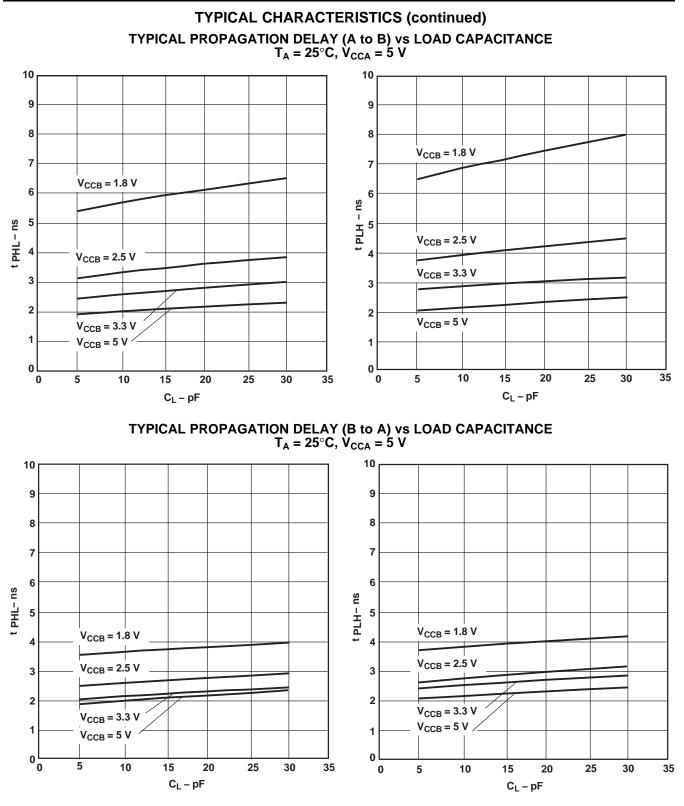
# SN74LVC1T45 SINGLE-BIT DUAL-SUPPLY BUS TRANSCEIVER WITH CONFIGURABLE VOLTAGE TRANSLATION AND 3-STATE OUTPUTS

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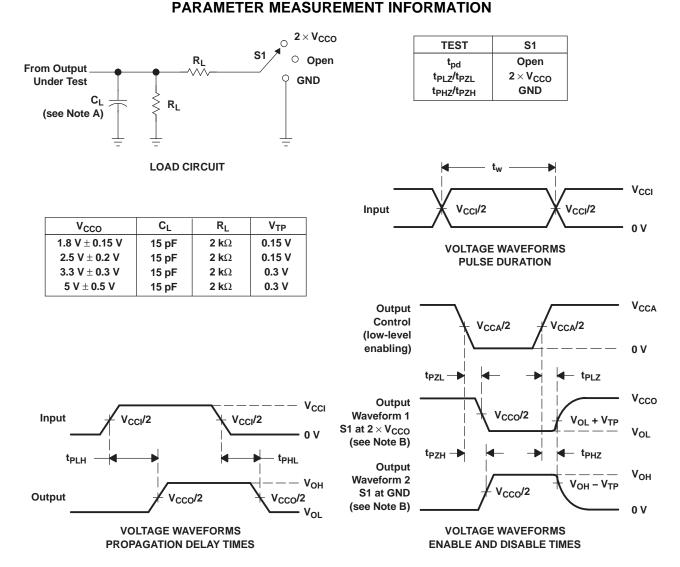


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- NOTES: A.  $C_L$  includes probe and jig capacitance.
  - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
    C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z<sub>Q</sub> = 50 Ω, dv/dt ≥ 1 V/ns.
  - D. The outputs are measured one at a time, with one transition per measurement.
  - E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
  - F.  $t_{PZI}$  and  $t_{PZH}$  are the same as  $t_{en}$ .
  - G.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .
  - H.  $V_{CCI}$  is the  $V_{CC}$  associated with the input port.
  - I.  $V_{CCO}$  is the  $V_{CC}$  associated with the output port.
  - J. All parameters and waveforms are not applicable to all devices.

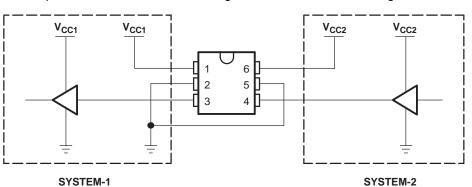
#### Figure 1. Load Circuit and Voltage Waveforms

### SN74LVC1T45 SINGLE-BIT DUAL-SUPPLY BUS TRANSCEIVER WITH CONFIGURABLE VOLTAGE TRANSLATION AND 3-STATE OUTPUTS SCES515H-DECEMBER 2003-REVISED JANUARY 2007



**APPLICATION INFORMATION** 

Figure 2 shows an example of the SN74LVC1T45 being used in a unidirectional logic level-shifting application.



PIN	NAME	FUNCTION	DESCRIPTION
1	V <sub>CCA</sub>	V <sub>CC1</sub>	SYSTEM-1 supply voltage (1.65 V to 5.5 V)
2	GND	GND	Device GND
3	A	OUT	Output level depends on V <sub>CC1</sub> voltage.
4	В	IN	Input threshold value depends on V <sub>CC2</sub> voltage.
5	DIR	DIR	GND (low level) determines B-port to A-port direction.
6	V <sub>CCB</sub>	V <sub>CC2</sub>	SYSTEM-2 supply voltage (1.65 V to 5.5 V)

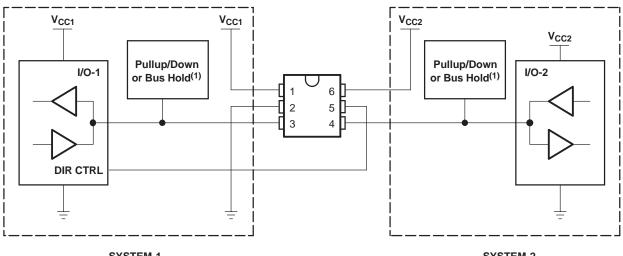
Figure 2. Unidirectional Logic Level-Shifting Application

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#### **APPLICATION INFORMATION**

Figure 3 shows the SN74LVC1T45 being used in a bidirectional logic level-shifting application. Since the SN74LVC1T45 does not have an output-enable (OE) pin, the system designer should take precautions to avoid bus contention between SYSTEM-1 and SYSTEM-2 when changing directions.



SYSTEM-1

SYSTEM-2

The following table shows data transmission from SYSTEM-1 to SYSTEM-2 and then from SYSTEM-2 to SYSTEM-1.

STATE	DIR CTRL	I/O-1	I/O-2	DESCRIPTION
1	Н	Out	In	SYSTEM-1 data to SYSTEM-2
2	Н	Hi-Z	Hi-Z	SYSTEM-2 is getting ready to send data to SYSTEM-1. I/O-1 and I/O-2 are disabled. The bus-line state depends on pullup or pulldown. <sup>(1)</sup>
3	L	Hi-Z	Hi-Z	DIR bit is flipped. I/O-1 and I/O-2 still are disabled. The bus-line state depends on pullup or pulldown. <sup>(1)</sup>
4	L	Out	In	SYSTEM-2 data to SYSTEM-1

(1) SYSTEM-1 and SYSTEM-2 must use the same conditions, i.e., both pullup or both pulldown.

#### Figure 3. Bidirectional Logic Level-Shifting Application

#### **Enable Times**

Calculate the enable times for the SN74LVC1T45 using the following formulas:

- $t_{P7H}$  (DIR to A) =  $t_{PI7}$  (DIR to B) +  $t_{PIH}$  (B to A)
- $t_{P7I}$  (DIR to A) =  $t_{PH7}$  (DIR to B) +  $t_{PHI}$  (B to A)
- $t_{PZH}$  (DIR to B) =  $t_{PLZ}$  (DIR to A) +  $t_{PLH}$  (A to B)
- $t_{PZL}$  (DIR to B) =  $t_{PHZ}$  (DIR to A) +  $t_{PHL}$  (A to B)

In a bidirectional application, these enable times provide the maximum delay from the time the DIR bit is switched until an output is expected. For example, if the SN74LVC1T45 initially is transmitting from A to B, then the DIR bit is switched; the B port of the device must be disabled before presenting it with an input. After the B port has been disabled, an input signal applied to it appears on the corresponding A port after the specified propagation delay.

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### PACKAGING INFORMATION

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Packag Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finisl	n MSL Peak Temp <sup>(3)</sup>
SN74LVC1T45DBVR	ACTIVE	SOT-23	DBV	6	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC1T45DBVRE4	ACTIVE	SOT-23	DBV	6	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC1T45DBVRG4	ACTIVE	SOT-23	DBV	6	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC1T45DBVT	ACTIVE	SOT-23	DBV	6	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC1T45DBVTE4	ACTIVE	SOT-23	DBV	6	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC1T45DBVTG4	ACTIVE	SOT-23	DBV	6	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC1T45DCKR	ACTIVE	SC70	DCK	6	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC1T45DCKRE4	ACTIVE	SC70	DCK	6	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC1T45DCKRG4	ACTIVE	SC70	DCK	6	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC1T45DCKT	ACTIVE	SC70	DCK	6	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC1T45DCKTE4	ACTIVE	SC70	DCK	6	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC1T45DCKTG4	ACTIVE	SC70	DCK	6	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC1T45DRLR	ACTIVE	SOT	DRL	6	4000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC1T45DRLRG4	ACTIVE	SOT	DRL	6	4000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC1T45YZPR	ACTIVE	DSBGA	YZP	6	3000	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details. **TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.



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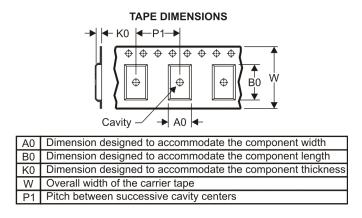
Enhanced Product: SN74LVC1T45-EP

NOTE: Qualified Version Definitions:

• Enhanced Product - Supports Defense, Aerospace and Medical Applications

### TAPE AND REEL INFORMATION





# QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

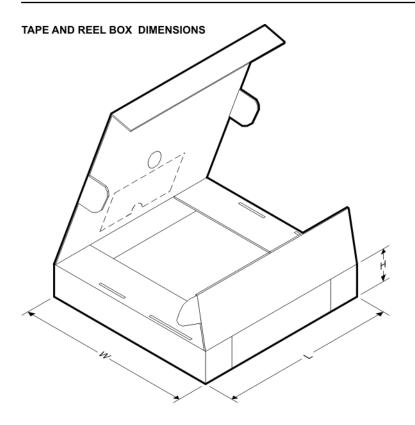


*All dimensions are nominal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LVC1T45DBVR	SOT-23	DBV	6	3000	180.0	9.2	3.23	3.17	1.37	4.0	8.0	Q3
SN74LVC1T45DBVT	SOT-23	DBV	6	250	180.0	9.2	3.23	3.17	1.37	4.0	8.0	Q3
SN74LVC1T45DCKR	SC70	DCK	6	3000	180.0	9.2	2.24	2.34	1.22	4.0	8.0	Q3
SN74LVC1T45DCKT	SC70	DCK	6	250	180.0	9.2	2.24	2.34	1.22	4.0	8.0	Q3
SN74LVC1T45DRLR	SOT	DRL	6	4000	180.0	9.2	1.78	1.78	0.69	4.0	8.0	Q3
SN74LVC1T45YZPR	DSBGA	YZP	6	3000	180.0	8.4	1.02	1.52	0.66	4.0	8.0	Q1
SN74LVC1T45YZPR	DSBGA	YZP	6	3000	180.0	8.4	1.02	1.52	0.66	4.0	8.0	Q1



# PACKAGE MATERIALS INFORMATION

22-Jul-2008



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LVC1T45DBVR	SOT-23	DBV	6	3000	202.0	201.0	28.0
SN74LVC1T45DBVT	SOT-23	DBV	6	250	202.0	201.0	28.0
SN74LVC1T45DCKR	SC70	DCK	6	3000	202.0	201.0	28.0
SN74LVC1T45DCKT	SC70	DCK	6	250	202.0	201.0	28.0
SN74LVC1T45DRLR	SOT	DRL	6	4000	202.0	201.0	28.0
SN74LVC1T45YZPR	DSBGA	YZP	6	3000	220.0	220.0	34.0
SN74LVC1T45YZPR	DSBGA	YZP	6	3000	220.0	220.0	34.0

DBV (R-PDSO-G6)

PLASTIC SMALL-OUTLINE PACKAGE

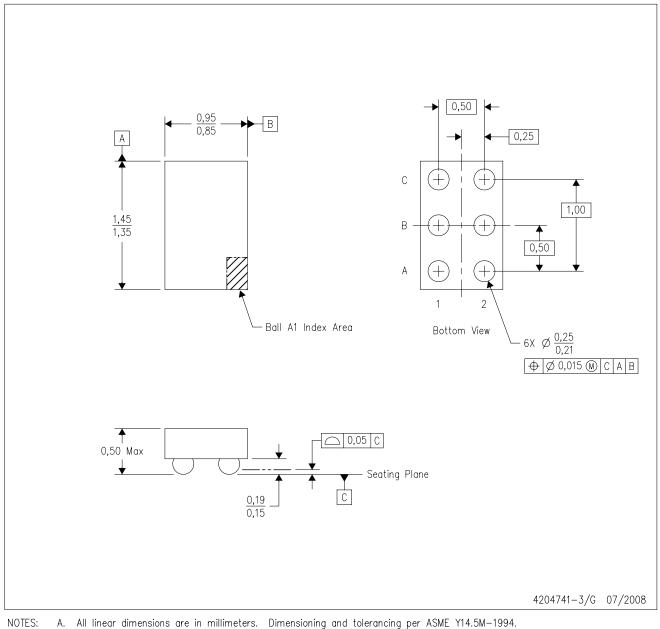


- NOTES:
- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
- D. Leads 1,2,3 may be wider than leads 4,5,6 for package orientation.
- È. Falls within JEDEC MO-178 Variation AB, except minimum lead width.



YZP (R-XBGA-N6)

DIE-SIZE BALL GRID ARRAY



- B. This drawing is subject to change without notice.
- C. NanoFree™ package configuration.
- D. This package is lead-free. Refer to the 6 YEP package (drawing 4204725) for tin-lead (SnPb).

NanoFree is a trademark of Texas Instruments.



DRL (R-PDSO-N6)

PLASTIC SMALL OUTLINE



NOTES:

A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994. B. This drawing is subject to change without notice.

🖄 Body dimensions do not include mold flash, interlead flash, protrusions, or gate burrs. Mold flash, interlead flash, protrusions, or gate burrs shall not exceed 0,15 per end or side.

D. JEDEC package registration is pending.



DCK (R-PDSO-G6)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES: A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
  - D. Falls within JEDEC MO-203 variation AB.



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